



**GP**  
**ELECTRONICS**

**GP1029SH**

**60V N- and P-Channel MOSFET**

### Product Summary

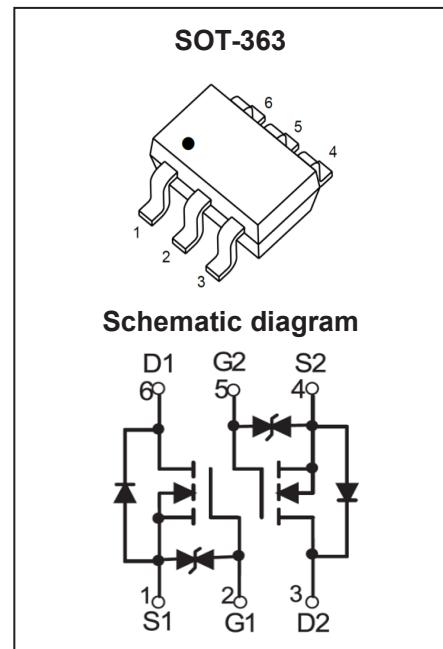
$V_{(BR)DSS}$	$R_{DS(on)TYP}$	$I_D$
60V	1.0Ω@10V	0.3A
	1.2Ω@4.5V	
-60V	1.9Ω@-10V	-0.19A
	2.5Ω@-4.5V	

### Feature

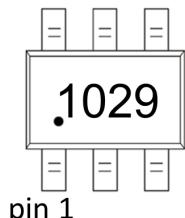
- Trench Technology Power MOSFET
- Low  $R_{DS(ON)}$
- Low Gate Charge
- ESD Protected

### Application

- Load Switch
- DC/DC Converter



### MARKING:



### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Value	Unit
Drain - Source Voltage	$V_{DS}$	60	-60	V
Gate - Source Voltage	$V_{GS}$	$\pm 20$	$\pm 20$	V
Continuous Drain Current <sup>1,5</sup>	$I_D$	0.3	-0.19	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	1.2	-0.76	A
Power Dissipation <sup>4,5</sup>	$P_D$	0.15	0.15	W
Thermal Resistance from Junction to Ambient <sup>5</sup>	$R_{\theta JA}$	833	833	°C/W
Junction Temperature	$T_J$	150	150	°C
Storage Temperature	$T_{STG}$	-55~+150	-55~+150	°C

**MOSFET ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$  unless otherwise noted)**
**NMOS:**

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Off Characteristics</b>						
Drain - Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	60			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 48\text{V}, V_{\text{GS}} = 0\text{V}$			1	$\mu\text{A}$
Gate - Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}} = \pm 20\text{V}, V_{\text{DS}} = 0\text{V}$			$\pm 3$	$\mu\text{A}$
<b>On Characteristics<sup>3</sup></b>						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1.0	1.4	3.0	V
Drain-source On-resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 0.3\text{A}$		1.0	3.0	$\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 0.1\text{A}$		1.2	4.0	
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 30\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$		24.6		pF
Output Capacitance	$C_{\text{oss}}$			3.7		
Reverse Transfer Capacitance	$C_{\text{rss}}$			1.1		
Gate Resistance	$R_g$	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$		143.3		$\Omega$
<b>Switching Characteristics</b>						
Total Gate Charge	$Q_g$	$V_{\text{DS}} = 30\text{V}, V_{\text{GS}} = 10\text{V}, I_D = 0.3\text{A}$		2.4		nC
Gate-source Charge	$Q_{\text{gs}}$			0.2		
Gate-drain Charge	$Q_{\text{gd}}$			0.5		
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 30\text{V}, V_{\text{GS}} = 10\text{V}, I_D = 300\text{mA}, R_G = 3\Omega$		4		ns
Turn-on Rise Time	$t_r$			17		
Turn-off Delay Ttime	$t_{\text{d}(\text{off})}$			10		
Turn-off Fall Time	$t_f$			48		
<b>Source - Drain Diode Characteristics</b>						
Diode Forward Voltage <sup>3</sup>	$V_{\text{SD}}$	$V_{\text{GS}} = 0\text{V}, I_s = 0.3\text{A}$			1.2	V

**OSFET ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$  unless otherwise noted)**
**PMOS:**

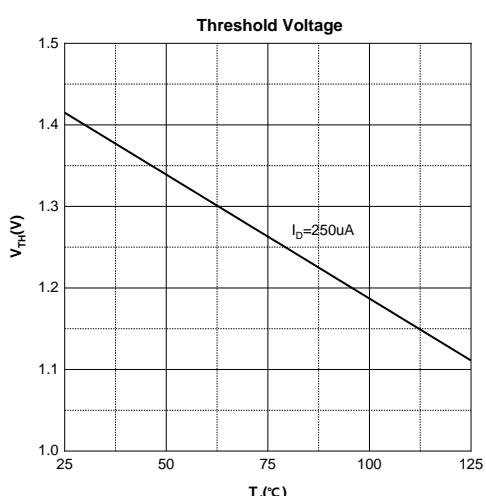
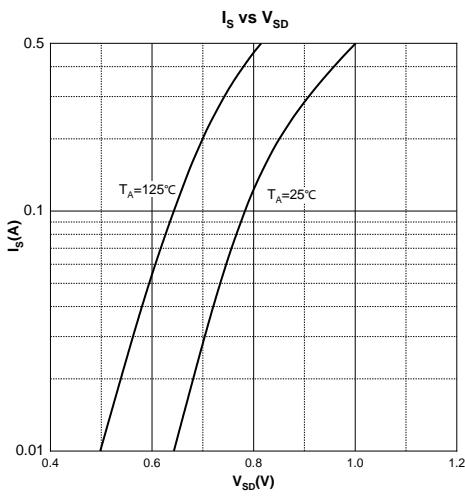
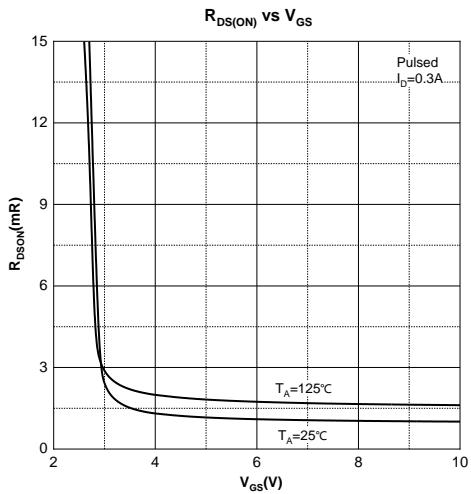
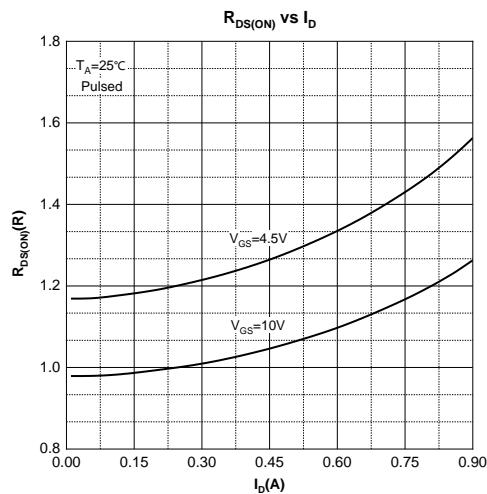
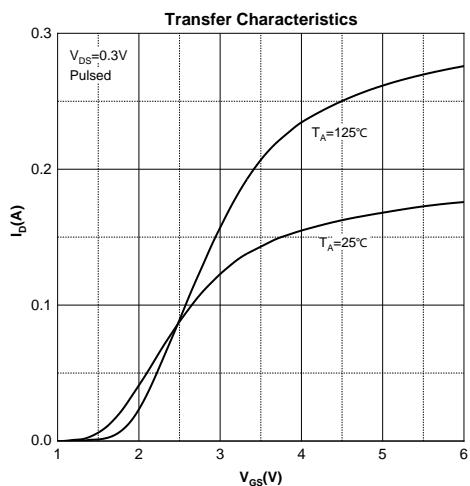
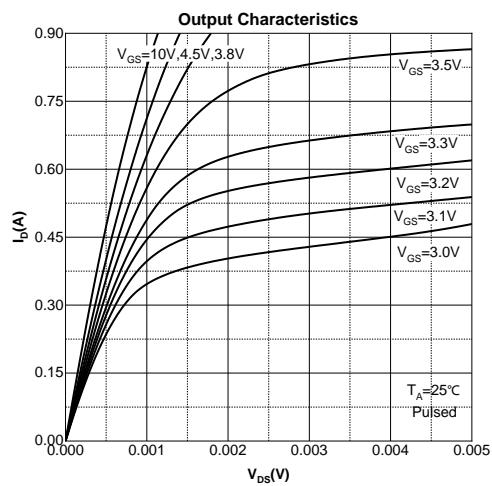
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Off Characteristics</b>						
Drain - Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = -250\mu\text{A}$	-60			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = -48\text{V}, V_{\text{GS}} = 0\text{V}$			-1	$\mu\text{A}$
Gate - Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}} = \pm 20\text{V}, V_{\text{DS}} = 0\text{V}$			$\pm 3$	$\mu\text{A}$
<b>On Characteristics<sup>3</sup></b>						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = -250\mu\text{A}$	-1.0	-1.7	-3.0	V
Drain-source On-resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = -10\text{V}, I_D = -0.1\text{A}$		1.9	4.0	$\Omega$
		$V_{\text{GS}} = -4.5\text{V}, I_D = -0.1\text{A}$		2.5	5.0	
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = -30\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$		27.8		pF
Output Capacitance	$C_{\text{oss}}$			5.3		
Reverse Transfer Capacitance	$C_{\text{rss}}$			2.9		
Gate Resistance	$R_g$	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$		153.8		$\Omega$
<b>Switching Characteristics</b>						
Total Gate Charge	$Q_g$	$V_{\text{DS}} = -30\text{V}, V_{\text{GS}} = -10\text{V}, I_D = -0.1\text{A}$		2.7		nC
Gate-source Charge	$Q_{\text{gs}}$			0.2		
Gate-drain Charge	$Q_{\text{gd}}$			1.1		
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = -30\text{V}, V_{\text{GS}} = -10\text{V}, I_D = -150\text{mA}, R_G = 3\Omega$		9		ns
Turn-on Rise Time	$t_r$			20		
Turn-off Delay Ttime	$t_{\text{d}(\text{off})}$			15		
Turn-off Fall Time	$t_f$			73		
<b>Source - Drain Diode Characteristics</b>						
Diode Forward Voltage <sup>3</sup>	$V_{\text{SD}}$	$V_{\text{GS}} = 0\text{V}, I_s = -0.1\text{A}$			-1.2	V

Notes :

- 1.The maximum current rating is limited by package.
- 2.Pulse Test : Pulse Width  $\leq 10\mu\text{s}$ , duty cycle  $\leq 1\%$ .
- 3.Pulse Test : Pulse Width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
- 4.The power dissipation  $P_D$  is limited by  $T_{J(\text{MAX})} = 150^\circ\text{C}$ .
- 5.Device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ .

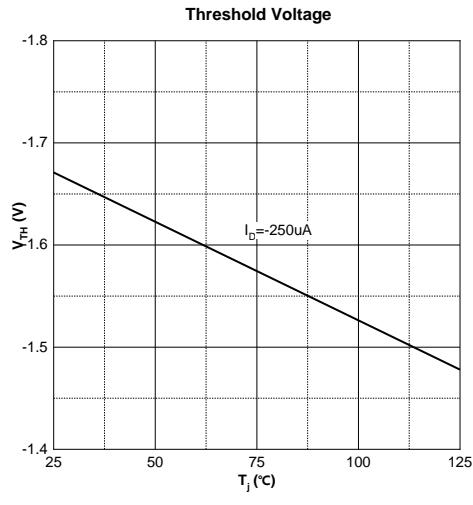
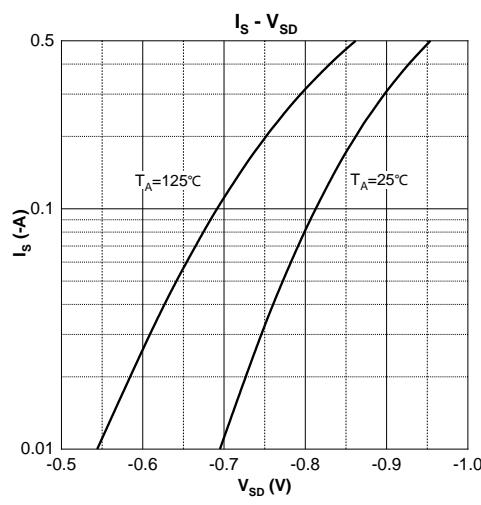
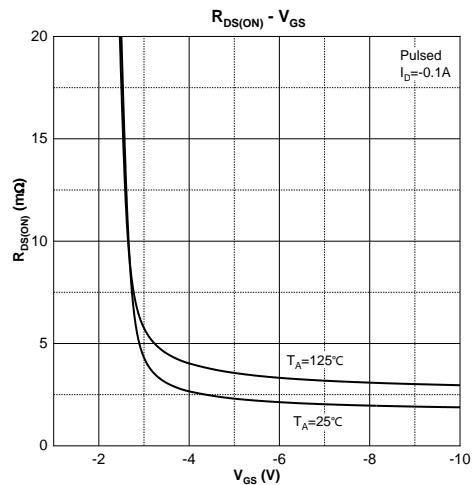
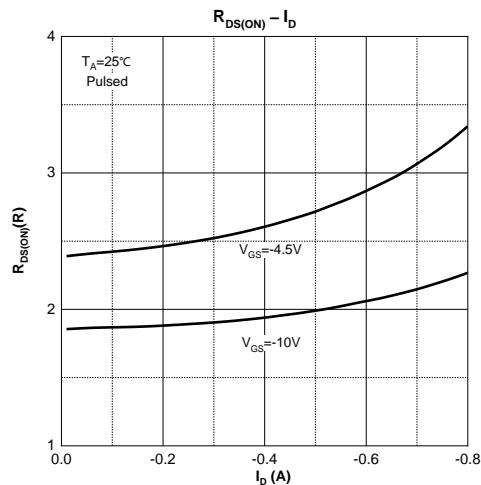
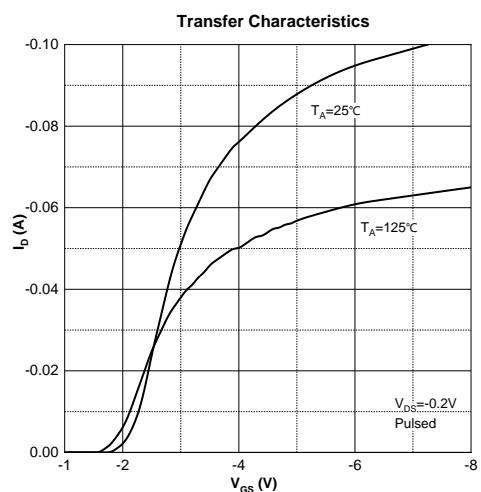
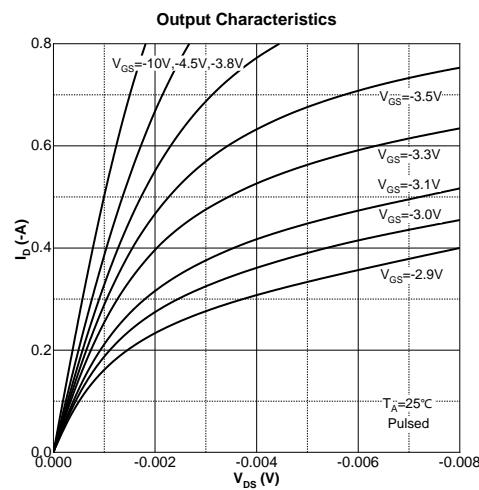
## Typical Characteristics

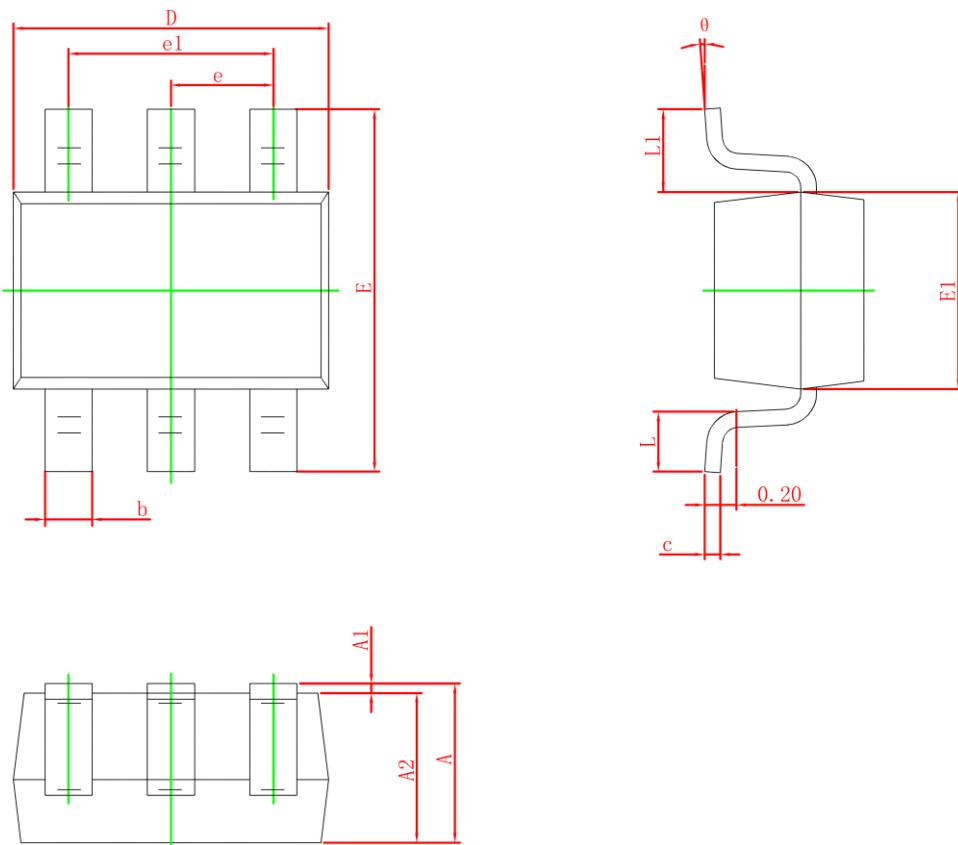
NMOS:



## Typical Characteristics

**PMOS:**



**SOT-363 Package Information**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A1	0	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.150	0.350	0.006	0.014
c	0.080	0.150	0.003	0.006
D	1.800	2.200	0.071	0.087
E	2.000	2.450	0.079	0.096
E1	1.150	1.350	0.045	0.053
e	0.650TYP		0.026TYP	
e1	1.200	1.400	0.047	0.055
L1	0.525REF		0.021REF	
L	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°